2019

中国IC封装材料技术与市场论坛

China IC Packaging Materials Tech & Market Forum

6.18-19 无锡 Wuxi

主办
Organizer

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会 议 背 景

半导体集成电路(IC)封装是指将晶圆按照产品型号及功能需求，加工到独立芯片的过程。IC 封装材料主要包括引线框架、封装基板、陶瓷封装材料、键合丝、包装材料、芯片粘结材料等，对芯片支撑、保护、散热、绝缘等有极为重要的作用。

亚化咨询估算，2018 年全球 IC 封装材料市场规模达 200 亿美元。当前，全球半导体封装材料的主要供应商包括日本信越化学、住友化工、京瓷化学、日立化成，德国巴斯夫、汉高、美国道康宁、杜邦等公司，占据主要市场份额，具有较大的市场影响力。随着中国 Fab 工厂陆续建成投运，未来 IC 封装材料市场增长空间巨大。由于中国 IC 市场快速增长，日月光、安靠、长电科技、通富微电、华天科技等全球领先的封测企业在中国增长迅速，也有利于未来国产化封装材料的应用。

亚化咨询预测，2019 年中国半导体封装材料市场规模将超 400 亿元人民币。如果中国未来进口大量芯片，将促进封装材料市场强劲增长，本土企业将迎来空前机遇。传统电子产品之外，汽车电子、AI、VR/AR 和物联网等终端的兴起，对先进封装工艺和材料的要求不断提高，相关企业将面临挑战。

由亚化咨询主办的**2019 中国 IC 封装材料技术与市场论坛**将于**6 月 18-19 日**在**无锡**召开。会议将探讨中国集成电路与 IC 封测产业政策趋势，全球及中国 IC 封装市场现状与展望，半导体封装工艺与材料进展与展望，中国 IC 封装材料与技术、设备的国产化，中国 IC 封装材料的供需情况及未来市场展望等。

会 议 主 题

- 中国集成电路与 IC 封测产业政策趋势
- 全球及中国集成电路与 IC 封装材料供需与展望
- 海外先进封装工艺与材料进展与动向
- 中国 IC 封装材料与技术、设备的国产化
- 高端制程处理器封装挑战及解决方案
- 后摩尔定律与先进封装
- 下游产品的封装材料与技术分布
- 2.5D、3D 扇出型封装技术的研发进展
- 其他先进封装材料与技术
- 未来封装与晶圆制造的整合趋势
- 工业参观&商务考察

日 程 安 排

2019 年 6 月 17 日 周一

16:00~21:00 会前注册

2019 年 6 月 18 日 周二

09:00~12:30 演讲报告

12:30~14:00 自助午餐与交流

14:00~18:30 演讲报告

18:30~20:00 招待晚宴

2019 年 6 月 19 日 周三

09:00~14:00 工业参观&商务考察

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Background

IC Packaging is the process of making wafer into integrated circuit according to the types and functions of products. IC packaging materials includes organic substrates, bonding wires, leadframes, encapsulation resins, die attach materials, thermal interface materials and others, which protect ICs from external impact, corrosion and so on.

According to the estimates from ASIACHEM Consulting, the global IC packaging materials market exceeds USD 20 billion in 2018. Shin-Etsu Chemical, Sumitomo Chemical, Kyocera Chemical, Hitachi, BASF, Henkel, Dow-Corning, and DuPont etc. are important suppliers in the world, and account for the dominant share and with significant impacts on the market. IC packaging materials market has huge growth space, as several large scale wafer fabrication plants go into production in China. Due to the rapid growth of China's IC market, the global leading packaging and testing companies such as ASE, Amkor, JCET, Tongfu Microelectronics and Huatian Technology are growing rapidly in China, which is also conducive to the application of domestic packaging materials.

China IC packaging materials market grows rapidly as the IC industry develops. ASIACHEM estimates that China semiconductor packaging materials market will exceed CNY 40 billion in 2019.

China IC packaging materials market will further grow if China imports more chips in the future and domestic companies will get unprecedented opportunities. While, as emerging demands from automobile, AI, VR/AR, IoT, and other terminals , related companies are also facing the challenge that requirements of advanced packaging process and materials.

China IC Packaging Materials Tech & Market Forum 2019 will be held in **June 18-19** in **Wuxi, Jiangsu Province** by ASIACHEM. The upcoming conference will discuss China IC and IC packaging industrial policy trend, localization of China IC packaging materials, technologies and equipments, Supply & demand of IC packaging materials market etc.

Preliminary Agenda

June 17, 2019	**Monday**
16:00~21:00	Pre-conference Registration
June 18, 2019	**Tuesday**
09:00~12:30	Speech
12:30~14:00	Networking Lunch
14:00~18:30	Speech
18:30~20:00	Banquet
June 19, 2019	**Wednesday**
09:00~14:00	Industry Travel

Topics

- China IC and IC Packaging Industrial Policy Trend
- Market Supply & Demand of Global & China IC Packaging Materials
- Progress and Trend of Advanced Packaging Technologies
- Localization of China IC Packaging Materials, Technologies and Equipments
- Challenges & Solutions of High-end Process Processor packaging
- Moore's Law and Advanced Packaging
- Distribution of Downstream Products Packaging Materials and Technologies
- Research Development of 2.5D, 3D Fans-out Packaging Technology
- Other advanced Packaging Materials and Technology
- Integration Trend of Packaging and Wafer Fabrication in the Future
- Onsite Visiting

English-Chinese Translation will be Provided